

élantec

# EL7581C 3-Channel DC:DC Converter

#### PRELIMINARY

#### Features

- TFT/LCD display supply
  - Boost regulator
  - V<sub>ON</sub> charge pump
  - VOFF charge pump
- 2V to 15V V<sub>IN</sub> supply
- $5V < V_{BOOST} < 18V$
- $5V < V_{ON} < 40V$
- $-40V < V_{OFF} < 0V$
- $V_{BOOST} = 5V @1A$
- V<sub>BOOST</sub> = 12V @700mA
- $V_{BOOST} = 15V @600mA$
- High frequency, small inductor DC:DC boost circuit
- Over 90% efficient DC:DC boost converter capability
- Adjustable frequency
- Adjustable soft-start
- Adjustable outputs
- · Small parts count

#### Applications

- TFT-LCD panels
- PDAs

## **Ordering Information**

Part No	Package	Tape & Reel	Outline #			
EL7581CRE	20-Pin HTSSOP		MDP0048			

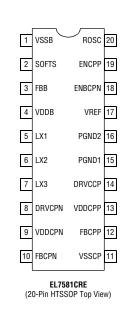
#### **General Description**

The EL7581C is a 3-channel DC:DC converter IC which is designed primarily for use in TFT/LCD applications. It features a 2.0V to 14V input capability and provides 5V to 18V output from a micropower boost converter. This output is designed to power the column drivers and can provide up to 600mA @15V, or 1A @5V output. A pair of charge pump control circuits provide regulated outputs of V<sub>ON</sub> and V<sub>OFF</sub> supplies at 8V to 40V and -5V to -40V, respectively (depending on the V<sub>BOOST</sub> set and external component configuration), each at up to 15mA.

The EL7581C features adjustable switching frequency, adjustable soft start, and each supply channel has a separate output enable control to allow selection of supply start-up sequence. An over-temperature feature is provided to allow the IC to be automatically protected from excessive power dissipation.

The EL7581C is available in a 20-pin HTSSOP package and is specified for operation over the full  $-40^{\circ}$ C to  $+85^{\circ}$ C temperature range.

#### **Connection Diagram**



CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures. 1-888-ELANTEC or 408-945-1323 | Intersil (and design) is a registered trademark of Intersil Americas Inc. Elantec ® is a registered trademark of Elantec Semiconductor, Inc. Copyright © Intersil Americas Inc. 2002. All Rights Reserved

# Absolute Maximum Ratings $(T_A = 25^{\circ}C)$

Values beyond absolute maximum ratings can cause the device to be per- manently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied					
V <sub>IN</sub> Input Voltage	14V				
V <sub>DDB</sub> , V <sub>DDCPB</sub> , V <sub>DDCPN</sub>	12V				
SW Voltage	18V				

Maximum Continuous Output Current	1A
Storage Temperature	-65°C to +150°C
Operating Ambient Temperature	-40°C to +85°C
Lead Temperature	300°C
Power Dissipation	See Curves
ESD Voltage	2kV

#### Important Note:

All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore:  $T_J = T_C = T_A$ 

#### **Electrical Characteristics**

 $V_{IN}=3.3V, V_{BOOST}=12V, I_{OUT}=450mA, F_{OSC}=1MHz, T_A=25^\circ C \text{ unless otherwise specified.}$ 

Parameter	Description	Condition	Min	Тур	Max	Unit
DC:DC Boost C	onverter					
IQ1	Quiescent Current - Shut-down	V(ENB) = 0V			10	μΑ
IQ2	Quiescent Current - Switching	$V(ENB) = V_{DDB}$ , frequency = 600kHz		5	8	mA
V(FBB)	Feedback Voltage		1.204	1.229	1.254	V
V <sub>REF</sub>	Reference Voltage		1.218	1.260	1.302	V
I(FBB)	Feedback Input Bias Current	Current magnitude			0.1	μΑ
V <sub>IN</sub>	Input Supply Range		2		14	V
D <sub>MAX</sub>	Maximum Duty Cycle		85	90		%
I(LX) <sub>MAX</sub>	Current Limit - Max Average Input Current	$V_{BOOST} = 15V, I(V_{BOOST}) = 500mA, V_{IN} = 2.7V$		3.2		А
R <sub>DS-ON</sub>	Switch On Resistance	at V <sub>BOOST</sub> = 10V, I(LX1+LX2+LX3+LX4) = 500mA		0.15		Ω
ILEAK-SWITCH	Switch Leakage Current				1	μΑ
V <sub>BOOST</sub>	Output Range	$V_{BOOST} > V_{IN} + V_{DIODE}$	5		15	
$\Delta V_{BOOST}\!/\!\Delta V_{IN}$	Line Regulation	$2.7V < V_{IN} < 13.2V, V_{BOOST} = 15V$			0.1	%
$\Delta V_{BOOST}\!/\!\Delta I_{O1}$	Load Regulation	$50mA < I_{O1} < 300mA$		0.5		%
FOSC-RANGE	Frequency Range	$R_{OSC}$ range = 240k $\Omega$ to 60k $\Omega$	200		1000	kHz
F <sub>OSC1</sub>	Switching Frequency	$R_{OSC} = 100k\Omega$	480	600	720	kHz
Fosc2	Switching Frequency	$R_{OSC} = 220k\Omega$	240	300	360	kHz
Positive Regulat	ed Charge Pump (V <sub>ON</sub> )					
		Most positive $V_{ON}$ output depends on the magni- tude of the $V_{DDCPP}$ input voltage (normally connected to $V_{BOOST}$ ) and the external component configuration (doubler or tripler)				
V <sub>DDCPP</sub>	Supply Input for Positive Charge Pump	Usually connected to VBOOST	5		15	V
V(FBCPP)	Feedback Reference Voltage		1.32	1.42	1.52	V
I(FBCPP)	Feedback Input Bias Current	Current magnitude			0.1	μΑ
I(DRCPP) <sub>MAX</sub>	Maximum RMS DRCPP Output Current	VDDCPP = 15V			80	mA
		VDDCPP = 6V			15	mA
F <sub>PUMP</sub>	Charge Pump Frequency	Frequency set by ROSC - see boost section		0.5*FOSC		Hz
Negative Regula	ted Charge Pump (V <sub>OFF</sub> )	•				
		Most negative $V_{OFF}$ output depends on the magnitude of the $V_{DDCPN}$ input voltage (normally connected to $V_{BOOST}$ ) and the external component configuration (doubler or tripler)				
VDDCPN	Supply Input for Negative Charge Pump	Usually connected to VBOOST	5		15	V

# EL7581C C:DC Converter PRELIMINARY 3-Channel DC:DC Converter

# **Electrical Characteristics**

 $V_{IN}$  = 3.3V,  $V_{BOOST}$  = 12V,  $I_{OUT}$  = 450mA,  $F_{OSC}$  = 1MHz,  $T_A$  = 25°C unless otherwise specified.

Parameter	Description	Condition	Min	Тур	Max	Unit
V(FBCPN)	Feedback Reference Voltage		-100	-50	0	mV
I(FBCPN)	Feedback Input Bias Current	Magnitude of input bias			0.1	μΑ
I(DRCPNf) <sub>MAX</sub>	Maximum Continuous RMS DRCPN	VDDCPN = 15V			80	mA
	Output Current	VDDCPN = 6V			15	mA
FPUMP	Charge Pump Frequency	Frequency set by ROSC - see boost section	0.5*Fosc		Hz	
Enable Control I	Logic	·				
V <sub>HI-ENX</sub>	Enable Input High Threshold	x = "BCPN", CPP"	1.6			v
V <sub>LO-ENX</sub>	Enable Input Low Threshold	x = "BCPN", CPP"			0.8	v
I(EN <sub>X</sub> )	Enable Input Bias Current	x = "BCPN", CPP"; current magnitude			0.1	μΑ
Over-Temperatu	ire Protection	·				
TOT	Over-temperature Threshold			140		°C
T <sub>HYS</sub>	Over-temperature Hysteresis			40		°C

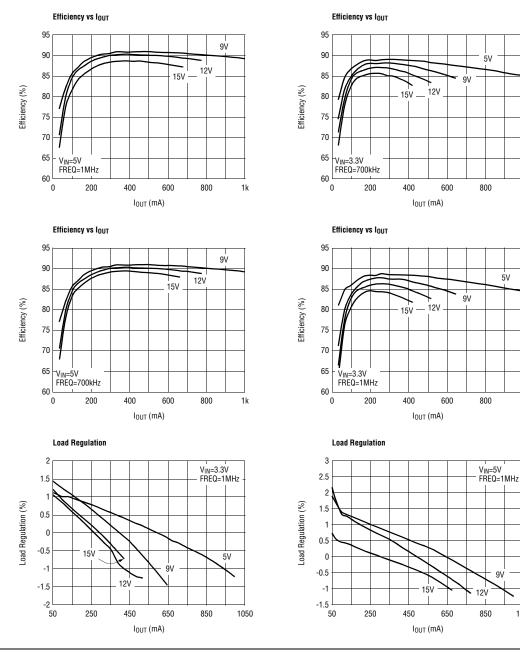
## **Pin Descriptions**

I = Input, O = Output, S = Supply

EL7581CRE 20-Pin HTSSOP	Pin Name	Pin Type	Pin Function	
1	VSSB	S	Ground for DC:DC boost and reference circuits; chip substrate	
2	SOFTS	I	Soft-start input; the capacitor connected to this pin sets the current limited start time	
3	FBB	I	Voltage feedback input for boost circuit; determines boost output voltage, VBOOST	
4	VDDB	S	Positive supply input for DC:DC boost circuits	
5	LX1	0	Boost regulator inductor drive pin 1	
6	LX2	0	Boost regulator inductor drive pin 2	
7	LX3	0	Boost regulator inductor drive pin 3	
8	DRVCPN	0	Driver output for the external generation of negative charge pump voltage, V <sub>OFF</sub>	
9	VDDCPN	S	Positive supply for input for VOFF generator	
10	FBCPN	Ι	Voltage feedback input to determine negative charge pump output, VOFF	
11	VSSCP	S	Negative supply pin for both the positive and negative charge pumps	
12	FBCPP	Ι	Voltage feedback to determine positive charge pump output, V <sub>ON</sub>	
13	VDDCPP	S	Positive supply input for V <sub>ON</sub> generator	
14	DRVCPP	0	Voltage driver output for the external generation of positive charge pump, $V_{\text{ON}}$	
15	PGND1	0	Power ground for LX switching FET	
16	PGND2	0	Power ground for LX switching FET	
17	VREF	I	Voltage reference for V <sub>COM</sub> and charge pump circuits; decouple to ground	
18	ENBCPN	Ι	Enable pin for the DC:DC boost function (V <sub>BOOST</sub> generation) and negative charge pump func (V <sub>OFF</sub> generation)	
19	ENCPP	I	Enable for DRVCPP (V <sub>ON</sub> generation); active high	
20	ROSC	Ι	Connected to an external resistor to ground; sets the switching frequency of the DC:DC boost	

#### PRELIMINARY





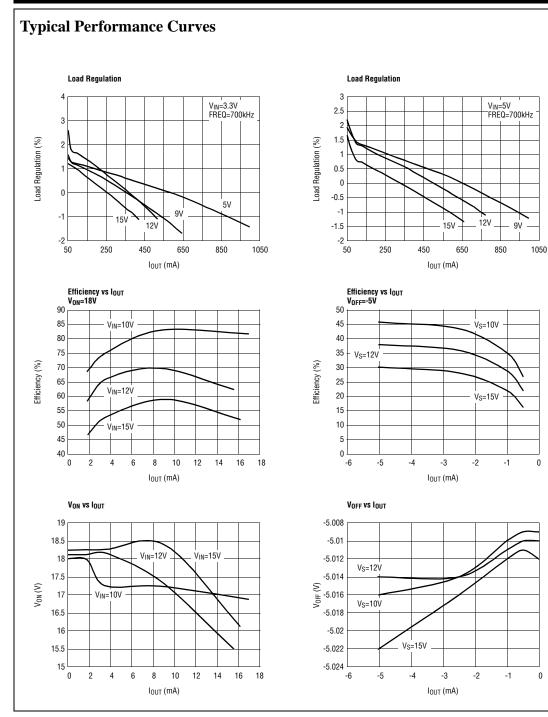
1k

1k

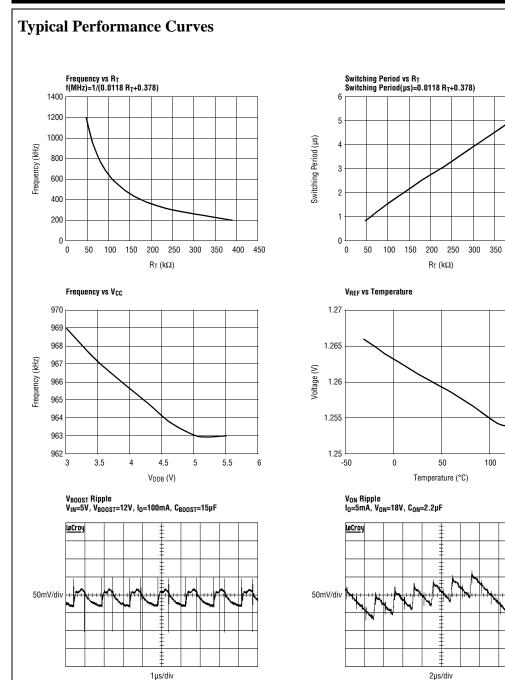
1050

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EL7581C



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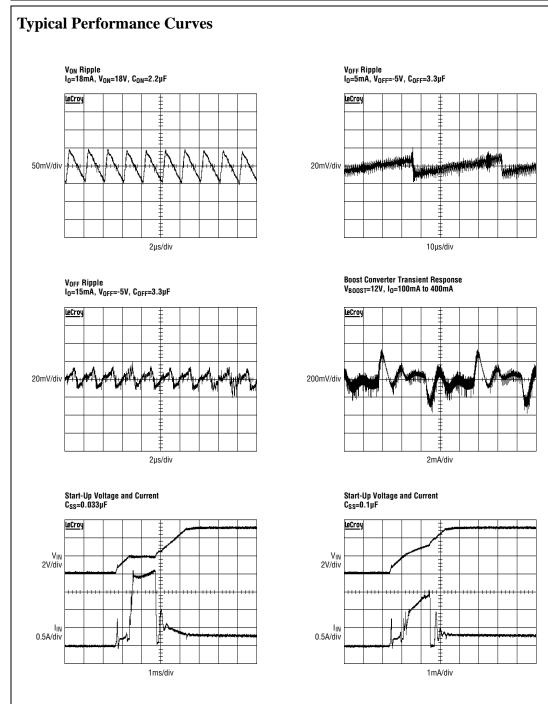


400 450

150

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EL7581C

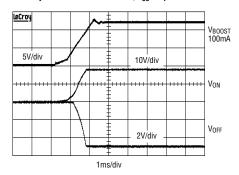


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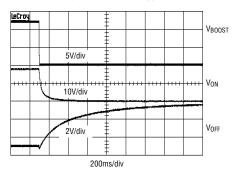
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# **Typical Performance Curves**

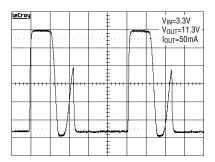


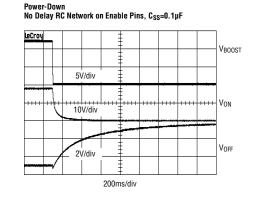


Power-Down 100k & 0.1µF Delay Network on ENCPP, C<sub>SS</sub>=0.1µF

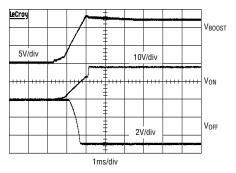


#### LX Waveform - Discontinuous Mode

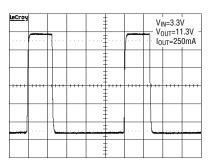




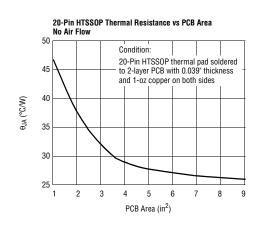
Power-Up 100k & 0.1 $\mu F$  Delay Network on ENCPP,  $C_{SS} {=} 0.1 \mu F$ 



#### LX Waveform - Continuous Mode



# **Typical Performance Curves**



#### PRELIMINARY

#### **Applications Information**

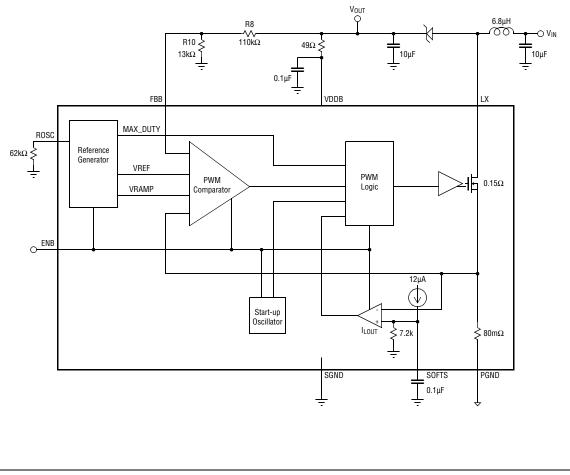
The EL7581C is high efficiency multiple output power solution designed specifically for thin-film transistor (TFT) liquid crystal display (LCD) applications. The device contains one high current boost converter and two low power charge pumps (V<sub>ON</sub> and V<sub>OFF</sub>).

The boost converter contains an integrated N-channel MOSFET to minimize the number of external components. The converter output voltage can be set from 5V to 18V with external resistors. The  $V_{ON}$  and  $V_{OFF}$  charge pumps are independently regulated to positive and negative voltages using external resistors. Output

voltages as high as 40V can be achieved with additional capacitors and diodes.

#### **Boost Converter**

The boost converter operates in constant frequency pulse-width-modulation (PWM) mode. Quiescent current for the EL7581C is only 5mA when enabled, and since only the low side MOSFET is used, switch drive current is minimized. 90% efficiency is achieved in most common application operating conditions.



A functional block diagram with typical circuit configuration is shown on the previous page. Regulation is performed by the PWM comparator which regulates the output voltage by comparing a divided output voltage with an internal reference voltage. The PWM comparator outputs its result to the PWM logic. The PWM logic switches the MOSFET on and off through the gate drive circuit. Its switching frequency is external adjustable with a resistor from timing control pin ( $R_T$ ) to ground. The boost converter has 200kHz to 1.2MHz operating frequency range.

#### Start-Up

After V<sub>DD</sub> reaches a threshold of about than 2V, the power MOSFET is controlled by the start-up oscillator, which generates fixed duty-ratio of 0.5-0.7 at a frequency of several hundred kilohertz. This will boost the output voltage, providing the initial output current load is not too great (< 250mA).

When  $V_{DD}$  reaches about 3.7V, the PWM comparator takes over the control. The duty ratio will be decided by the multiple-input direct summing comparator, Max\_Duty signal (about 90% duty-ratio), and the Current Limit Comparator, whichever is the smallest.

The soft-start is provided by the current limit comparator. As the internal  $12\mu$ A current source changes the external soft-start capacitor, the peak MOSFET current is limited by the voltage on the capacitor. This in turn controls the rising rate of output voltage.

The regulator goes through the start-up sequence as well after the ENB signal is pulled to HI.

#### **Steady-State Operation**

When the output reaches the preset voltage, the regulator operates at steady state. Depending on the input/output condition and component, the inductor operates at either continuous-conduction mode or discontinuous-conduction mode.

In the continuous-conduction mode, the inductor current is a triangular waveform and LX voltage a pulse waveform. In the discontinuous-conduction mode, the inductor current is complete dry out before the MOSFET is turned on again. The input voltage source, the inductor, and the MOSFET and output diode parasitic capacitors forms a resonant circuit. Oscillation will occur in this period. This oscillation is normal and will not affect the regulation.

At very low load, the MOSFET will skip pulse sometimes. This is normal.

#### **Current Limit**

The MOSFET current limit is nominal 3.2A. This restricts the maximum output current  $I_{OMAX}$  based on the following formula:

$$I_{OMAX} = \left(3.2 \ \mathbb{D} \frac{\Delta I_L}{2}\right) \times \frac{V_{IN}}{V_O}$$

where:

 $\Delta I_{\rm L}$  is the inductor peak-to-peak current ripple and is decided by:

$$\Delta I_L = \frac{V_{IN}}{L} \times \frac{D}{F_S}$$

D is the MOSFET turn-on radio and is decided by:

$$D = \frac{V_O \oplus V_{IN}}{V_O}$$

 $F_S$  is the switching frequency.

The following table gives typical values:

#### **Maximum Continuous Output Current**

$V_{IN}(V)$	<b>V</b> <sub>0</sub> (V)	L (µH)	Fs (kHz)	I <sub>OMAX</sub> (mA)
3	5	10	700	1000
3	9	10	700	550
3	12	10	700	450
4.5	9	10	700	850
4.5	12	10	700	700
4.5	15	10	700	600
9	12	10	700	1000
9	15	10	700	800
12	18	10	700	1000

#### **Component Considerations**

#### **Input Capacitor**

It is recommended that  $C_{IN}$  is larger than  $10\mu F.$  Theoretically, the input capacitor has ripple current of  $\Delta I_L.$  Due

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to high-frequency noise in the circuit, the input current ripple may exceed the theoretical value. Larger capacitor will reduce the ripple further.

#### **Boost Inductor**

The inductor has peak and average current decided by:

$$I_{LPK} = I_{LAVG} + \frac{\Delta I_L}{2}$$
$$I_{LAVG} = \frac{I_O}{1 DD}$$

The inductor should be chosen to be able to handle this current. Furthermore, due to the fixed internal compensation, It is recommended that maximum inductance of  $10\mu$ H and  $15\mu$ H to be used in the 5V and 12V or higher output voltage, respectively.

The output diode has average current of  $I_{O}$ , and peak current the same as the inductor's peak current. Schottky diode is recommended and it should be able to handle those currents.

Output voltage ripple is the product of peak inductor current times the ESR of output capacitor. Low ESR capacitor is to be used to reduce the output ripple. The minimum out capacitance of  $330\mu$ F,  $47\mu$ F, and  $33\mu$ F is recommended for 5V, 12V, and 16V for 600kHz switching frequency, respectively. For 1MHz switching frequency,  $220\mu$ F,  $33\mu$ F, and  $22\mu$ F capacitor can be used for the output voltages. In addition to the voltage rating, the output capacitor should also be able to handle the rms current is given by:

$$I_{CORMS} = \sqrt{(1 \oplus D) \times \left(D + \frac{\Delta I_L^2}{I_{LAVG}^2} \times \frac{1}{12}\right)} \times I_{LAVG}$$

#### Feedback Resistor Network

An external resistor divider is required to divide the output voltage down to the nominal reference voltage. Current drawn by the resistor network should be limited to maintain the overall converter efficiency. The maximum value of the resistor network is limited by the feedback input bias current and the potential for noise being coupled into the feedback pin. A resistor network in the order of  $200k\Omega$  is recommended. The boost converter output voltage is determined by the following relationship:

$$V_{OUT} = \frac{R_8 + R_{10}}{R_{10}} \times V_{FBB}$$

A 3.9nF compensation capacitor across the feedback resistor to ground is recommended to keep the converter in stable operation at low output current and high frequency conditions.

#### Schottky Diode

Speed, forward voltage drop, and reverse current are the three most critical specifications for selecting the Schottky diode. The entire output current flows through the diode, so the diode average current is the same as the average load current and the peak current is the same as the inductor peak current. When selecting the diode, one must consider the forward voltage drop at the peak diode current. On the elantec demo board, MBRM120 is selected. Its forward voltage drop is 450mV at 1A forward current.

#### **Output Capacitor**

The EL7581C is specially compensated to be stable with capacitors which have a worst-case minimum value of  $10\mu$ F at the particular V<sub>OUT</sub> being set. Output ripple voltage requirements also determine the minimum value and the type of capacitors. Output ripple voltage consists of two components - the voltage drop caused by the switching current though the ESR of the output capacitor: and the charging and discharging of the output capacitor:

$$V_{RIPPLE} = I_{PEAK} \times ESR + \frac{V_{OUT} \boxdot V_{IN}}{V_{OUT}} \times \frac{I_{OUT}}{C_{OUT} \times FREQ}$$

For low ESR ceramic capacitors, the output ripple is dominated by the charging/discharging of the output capacitor.

#### V<sub>OUT-BOOST</sub> > 12V

The maximum voltage rating for the boost converter power supply input pin,  $V_{DDB}$ , is 12V. This voltage is used to power the internal power FET for optimum efficiency and reliable operations,  $V_{DDB}$  voltage should be maintained between 10V to 12V. For boost converter output voltage greater than 12V, there are two

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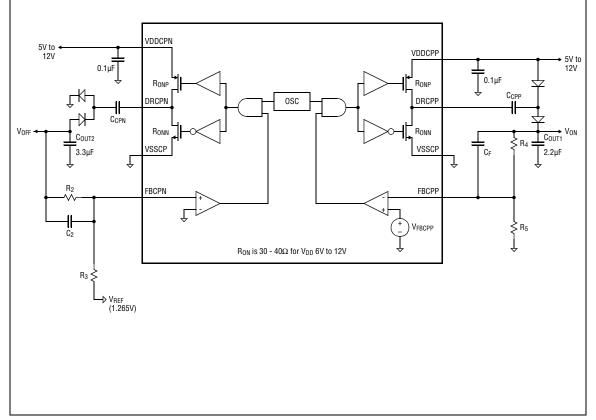
approaches to reducing the voltage from V<sub>OUT-BOOST</sub> to V<sub>DDB</sub>. The first approach is to use a Zener diode to lower the V<sub>OUT-BOOST</sub> going into the V<sub>DDB</sub> pin. The second approach is to increase the V<sub>OUT-BOOST</sub> to V<sub>DDB</sub> series resistor value. The I<sub>DD-BOOST</sub> vs F<sub>SW</sub> curve is shown in the typical performance curves section of the datasheet. The necessary series resistor value can be calculated from the I<sub>DD-BOOST</sub> vs F<sub>SW</sub> curve and the boost converter output voltage.

# Positive and Negative Charge Pump $(V_{ON} \mbox{ and } V_{OFF})$

The EL7581C contains two independent charge pumps, see charge pump block and connection diagram. The

negative charge pump inverts the V<sub>DDCPN</sub> supply voltage and provides a regulated negative output voltage. The positive charge pump doubles the V<sub>DDCPP</sub> supply voltage and provides a regulated positive output voltage. The regulation of both the negative and positive charge pumps is generated by the internal comparator that senses the output voltage and compares it with and internal reference. The switching frequency of the charge pump is set to  $\frac{1}{2}$  the boost converter switching frequency.

The pumps use pulse width modulation to adjust the pump period, depending on the load present. The pumps are short circuit-protected and can supply 15mA to 80mA for  $V_{DD}$  6V to 15V.



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#### **Positive Charge Pump Design Considerations**

A single stage charge pump is shown above. The maximum  $V_{\rm ON}$  output voltage is determined by the following equation:

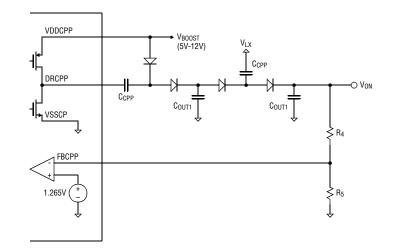
$$\begin{split} &V_{ON}(max) \leq 2 \times VDDCPP \ \mbox{D} \ I_{OUT} \times 2 \times (R_{ONN} + R_{ONP}) \ \mbox{D} \\ &2 \times V_{DIODE} \ \mbox{D} \ I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{CPP}} \ \mbox{D} \ I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{OUT1}} \end{split}$$

**Two-Stage Positive Charge Pump Circuit** 

#### where:

 $R_{ONN}$  and  $R_{ONP}$  resistance values depend on the  $V_{DDCPP}$  voltage levels. For 15V supply,  $R_{ON}$  is typically 30V. For 6V supply,  $R_{ON}$  is typically 40 $\Omega$ 

If additional stage is required, the LX switching signal is recommended to drive the additional charge pump diodes. The drive impedance at the LX switching is typically  $150m\Omega$ . The figure on the next page illustrates an implementation for two-stage positive charge pump circuit.



The maximum  $V_{\mbox{ON}}$  output voltage for N+1 stage charge pump is:

$$\begin{split} V_{ON}(max) &\leq 2 \times VDDCPP \oplus I_{OUT} \times 2 \times (R_{ONN} + R_{ONP}) \oplus 2 \times V_{DIODE} \oplus I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{CPP}} \oplus I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{OUT1}} + N \times V_{LX}(max) \oplus N \times \left(2 \times V_{DIODE} + I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{CPP}} + I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{OUT1}}\right) \end{split}$$

 $R_4$  and  $R_{12}$  set the  $V_{ON}$  output voltage:

$$V_{ON} = V_{FBCPP} \times \frac{R_4 + R_5}{R_5}$$

Similar to positive charge pump, if additional stage is required, the LX switching signal is recommended to

drive the additional charge pump diodes. The figure on

the next page shows a two stage negative charge pump

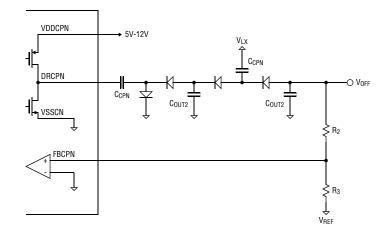
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#### **Negative Charge Pump Design Considerations**

The criteria for the negative charge pump is similar to the positive charge pump. For a single stage charge pump, the maximum  $V_{OFF}$  output voltage is:

$$\begin{split} &V_{OFF}(max) \geq I_{OUT} \times 2 \times (R_{ONN} + R_{ONNP}) + 2 \times V_{DIODE} \oplus I_{OUT} \times \\ & \frac{1}{0.5 \times F_{SQ} \times C_{CPN}} \oplus I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{OUT2}} \oplus VDDCPN \end{split}$$

**Two-Stage Negative Charge Pump Circuit** 



circuit.

The maximum  $V_{OFF}$  output voltage for N+1 stage charge pump is:

$$\begin{split} &V_{OFF}(max) \geq I_{OUT} \times 2 \times (R_{ONN} + R_{ONNP}) + 2 \times V_{DIODE} \oplus I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{CPN}} \oplus I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{OUT2}} \oplus V_{DDCPN} \oplus N \times V_{LX}(max) + N \times \left(2 \times V_{DIODE} + I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{CPN}} + I_{OUT} \times \frac{1}{0.5 \times F_{SW} \times C_{OUT2}}\right) \end{split}$$

 $R_2$  and  $R_3$  determine V<sub>OFF</sub> output voltage:

$$V_{OFF} = -(V_{REF} \oplus V_{FBCPN}) \times \frac{R_2}{R_3} + V_{FBCPN}$$

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#### **Over-Temperature Protection**

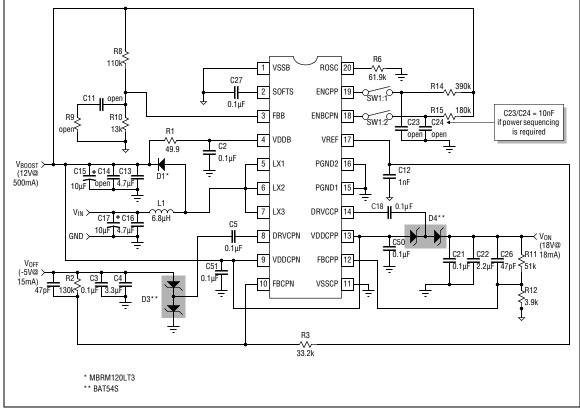
An internal temperature sensor continuously monitors the die temperature. In the event that die temperature exceeds the thermal trip point, the device will shut down and disable itself. The upper and lower trip points are typically set to 140°C and 100°C respectively.

#### **PCB Layout Guidelines**

Careful layout is critical in the successful operation of the application. The following layout guidelines are recommended to achieve optimum performance.

- 1. V<sub>REF</sub> and V<sub>DDB</sub> bypass capacitors should be placed next to the pins.
- 2. Place the boost converter diode and inductor close to the LX pins.

- 3. Place the boost converter output capacitor close to the PGND pins.
- 4. Locate feedback dividers close to their respected feedback pins to avoid switching noise coupling into the high impedance node.
- Place the charge pump feedback resistor network after the diode and output capacitor node to avoid switching noise; a demo board is available to illustrate the proper layout implementation.
- All low-side feedback resistors should be connected directly to V<sub>SSB</sub>. V<sub>SSB</sub> should be connected to the power ground close to the negative terminal of C<sub>OUT</sub>.



#### **Typical Application Circuit**

# *EL7581C* EL7581C

**3-Channel DC:DC Converter** 

PRELIMINARY

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